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<b>TRANSMITTAL FORM</b> (to be used for all correspondence after initial filing)	Application Number	09/995,866	
	Filing Date	November 29, 2001	
	First Named Inventor	Akira MASE et al.	
	Group Art Unit	1732	
	Examiner Name	Unassigned	
Total Number of Pages in This Submission	4	Attorney Docket Number	0756-2401

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- 1 -

Docket No. 0756-2401

7/ Pre Amndt A  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: )

Akira MASE et al. )

Serial No. 09/995,866 )

Filed: November 29, 2001 )

For: CONDUCTIVE PATTERN PRODUCING )

METHOD AND ITS APPLICATIONS )

Examiner: Unassigned

Group Art Unit: 1732

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PRELIMINARY AMENDMENT

Commissioner for Patents  
Washington, DC 20231

Sir:

Please preliminarily amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 1 in its entirety.

Please add new claims 2-9 as follows:

--2. A display device comprising:

a glass substrate;

a lead formed over the glass substrate, said lead comprising a first layer comprising silver and a second layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second layer of the lead.

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